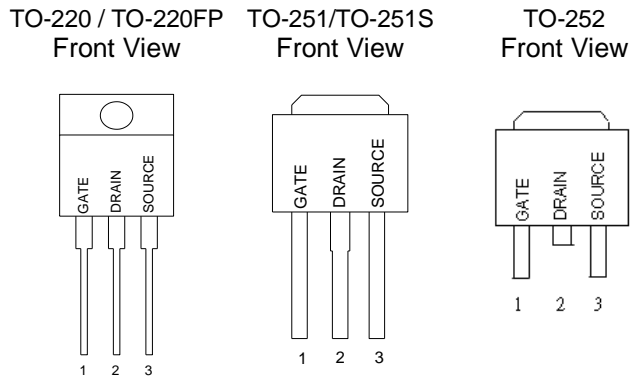




GENERAL DESCRIPTION

This advanced high voltage MOSFET is designed to withstand high energy in the avalanche mode and switch efficiently. This new high energy device also offers a drain-to-source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits.

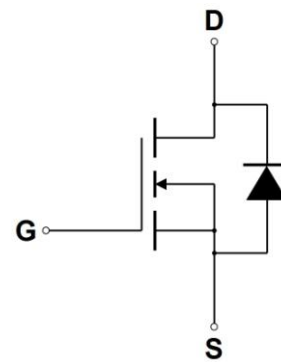
PIN CONFIGURATION



FEATURES

- ◆ SJ MOS
- ◆ Higher Current Rating
- ◆ Lower Rds(on)
- ◆ Lower Capacitances
- ◆ Lower Total Gate Charge

SYMBOL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Drain to Current — Continuous	I_D	2.3	A
— Pulsed	I_{DM}	6.9	A
Gate-to-Source Voltage — Continue	V_{GS}	±20	V
Total Power Dissipation TO-220	P_D	60	W
TO-220FP		24	
TO-251/TO-251S/TO-252		35.7	
Derate above 25°C TO-220		0.5	
TO-220FP		0.2	
TO-251/TO-251S/TO-252		0.29	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C
Single Pulse Drain-to-Source Avalanche Energy — $T_J = 25^\circ\text{C}$ ($V_{DD} = 100\text{V}, V_{GS} = 10\text{V}, I_L = 1.0\text{A}, L = 10\text{mH}, R_G = 25\Omega$)	E_{AS}	5	mJ
Thermal Resistance — Junction to Case TO-220	θ_{JC}	2.1	°C/W
TO-220FP		5.3	
TO-251/TO-251S/TO-252		3.5	
— Junction to Ambient TO-251/TO-251S/TO-252/TO-220/TO-220FP	θ_{JA}	100	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T_L	260	°C



ORDERING INFORMATION

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM02S60XN251 (Note1)	GWM02S60X	TO-251	Tube	
GWM02S60XN251S (Note1)	GWM02S60X	TO-251S	Tube	
GWM02S60XN252 (Note1)	GWM02S60X	TO-252	Tube	
GWM02S60XN252TR (Note1)	GWM02S60X	TO-252	Tape and Reel	
GWM02S60XN220 (Note1)	GWM02S60X	TO-220	Tube	
GWM02S60XN220FP (Note1)	GWM02S60X	TO-220FP	Tube	
GWM02S60GN251 (Note1)	GWM02S60G	TO-251	Tube	
GWM02S60GN251S (Note1)	GWM02S60G	TO-251S	Tube	
GWM02S60GN252 (Note1)	GWM02S60G	TO-252	Tube	
GWM02S60GN252TR (Note1)	GWM02S60G	TO-252	Tape and Reel	
GWM02S60GN220 (Note1)	GWM02S60G	TO-220	Tube	
GWM02S60GN220FP (Note1)	GWM02S60G	TO-220FP	Tube	

Note1: X : Suffix for Halogen Free and PB Free Product / G : Suffix for PB Free Product

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^\circ\text{C}$.

Characteristic		Symbol	GWM02S60			Units
			Min	Typ	Max	
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$)		$V_{(BR)DSS}$	600			V
Drain-Source Leakage Current ($V_{DS} = 600\text{ V}$, $V_{GS} = 0\text{ V}$)		I_{DSS}			1	μA
Gate-Source Leakage Current-Forward ($V_{gsf} = 20\text{ V}$, $V_{DS} = 0\text{ V}$)		I_{GSSF}			100	nA
Gate-Source Leakage Current-Reverse ($V_{gsr} = -20\text{ V}$, $V_{DS} = 0\text{ V}$)		I_{GSSR}			100	nA
Gate Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{ A}$)		$V_{GS(th)}$	2		4	V
Static Drain-Source On-Resistance ($V_{GS} = 10\text{ V}$, $I_D = 0.67\text{ A}$) *		$R_{DS(on)}$			2.6	Ω
Input Capacitance	$(V_{DS} = 100\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1.0\text{ MHz}$)	C_{iss}		146		pF
Output Capacitance		C_{oss}		11		pF
Reverse Transfer Capacitance		C_{rss}		20		pF
Turn-On Delay Time	$(V_{DD} = 300\text{ V}$, $I_D = 2\text{ A}$, $V_{GS} = 10\text{ V}$, $R_G = 9.1\Omega$) *	$t_{d(on)}$		6.6		ns
Rise Time		t_r		20		ns
Turn-Off Delay Time		$t_{d(off)}$		15.6		ns
Fall Time		t_f		22		ns
Total Gate Charge	$(V_{DS} = 480\text{ V}$, $I_D = 2\text{ A}$, $V_{GS} = 10\text{ V}$)*	Q_g		24.6		nC
Gate-Source Charge		Q_{gs}		13.3		nC
Gate-Drain Charge		Q_{gd}		37.9		nC
SOURCE-DRAIN DIODE CHARACTERISTICS						
Forward On-Voltage(1)	$(I_S = 2\text{ A}$, $dI_S/dt = 100\text{ A}/\mu\text{s}$)	V_{SD}			1.5	V
Forward Turn-On Time		t_{on}		**		ns
Reverse Recovery Time		t_{rr}		142.2		ns

* Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$

** Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS

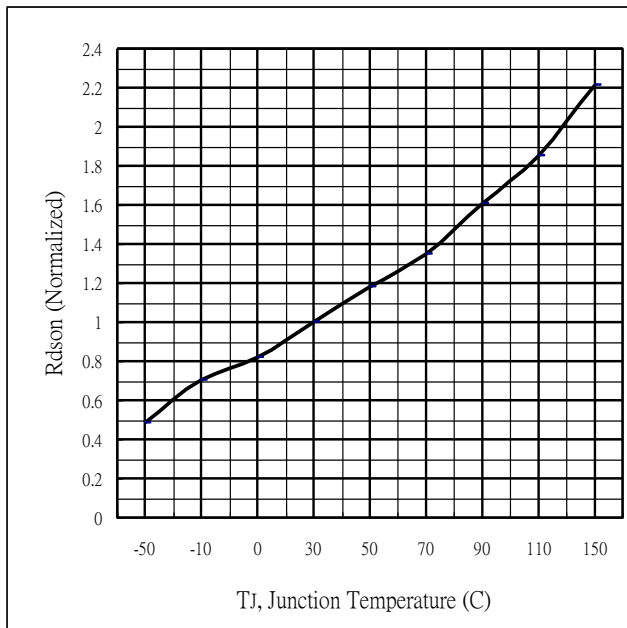


Fig 1. On-Resistance Variation with vs. Temperature

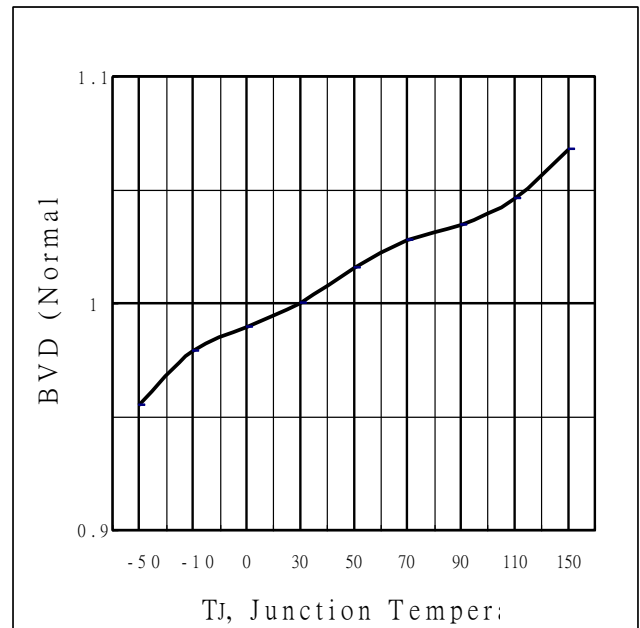


Fig.2 Breakdown Voltage Variation vs. Temperature

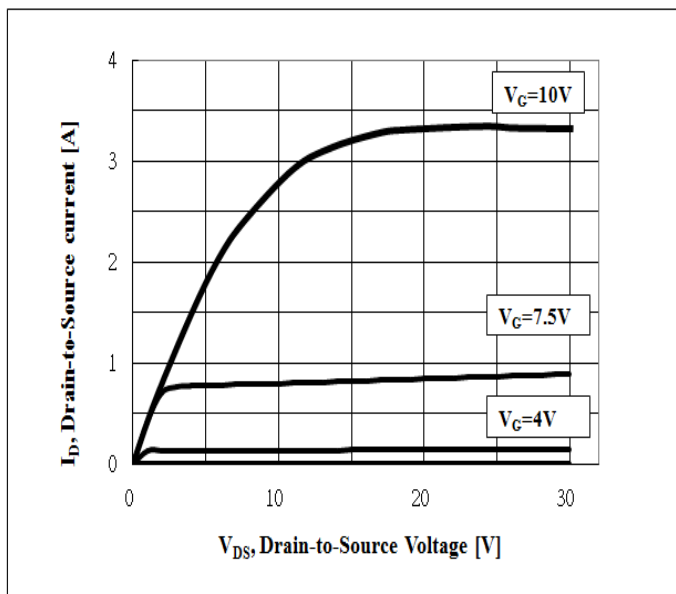


Fig 3. Typical Output Characteristics

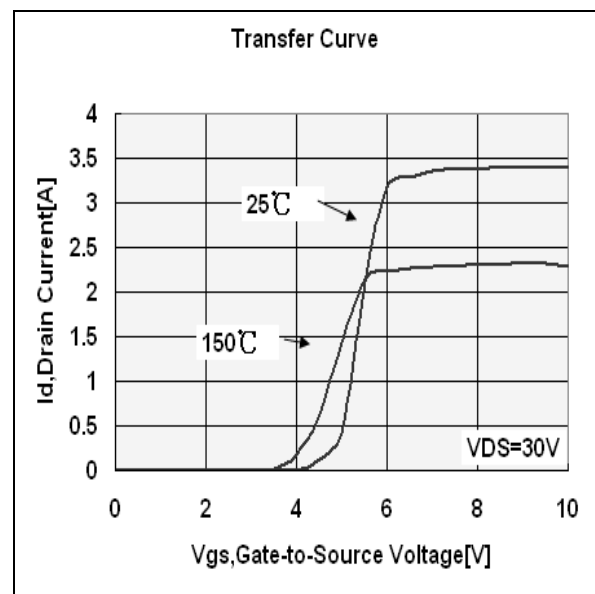


Fig 4. Typical Transfer Characteristics

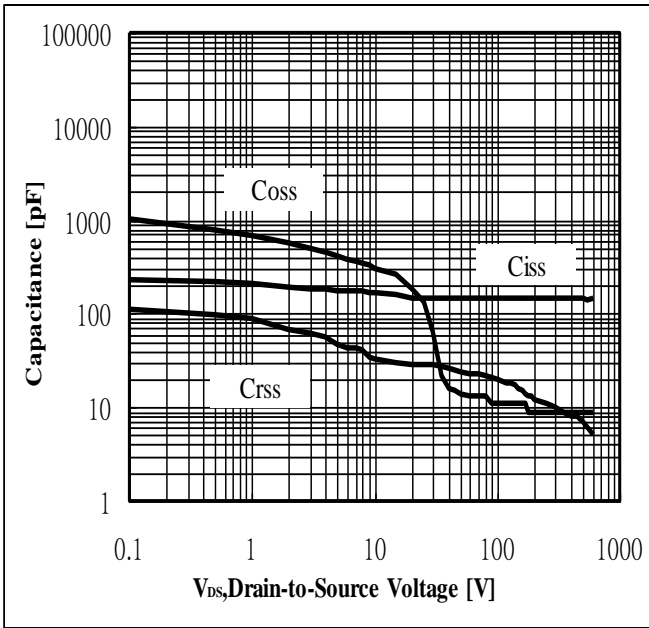


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

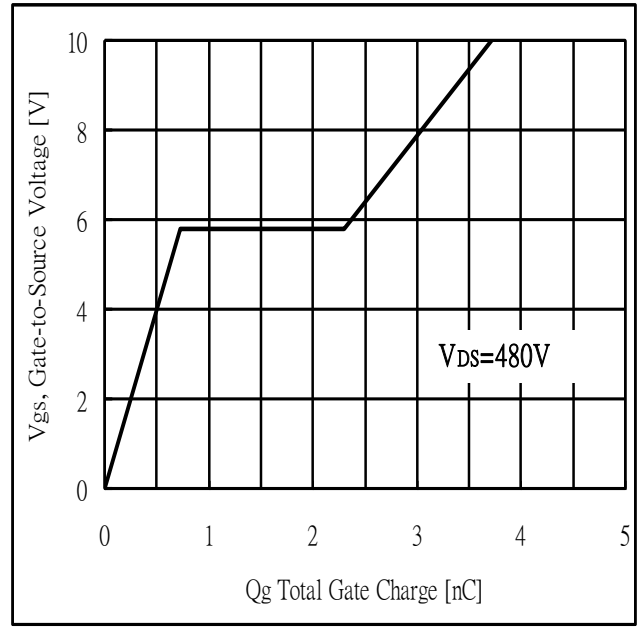


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage